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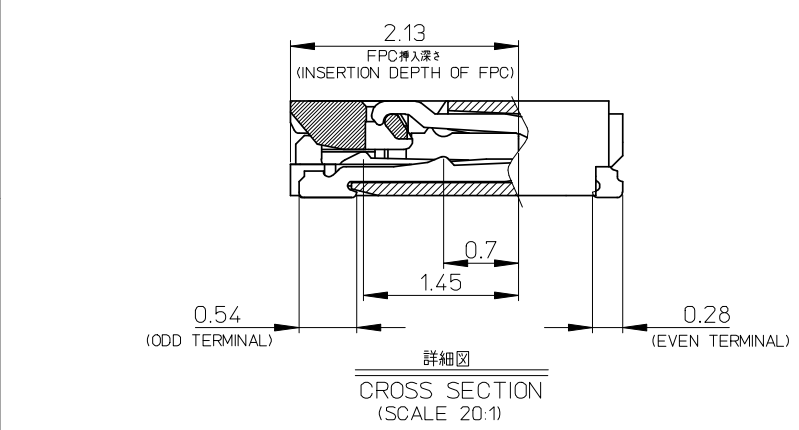
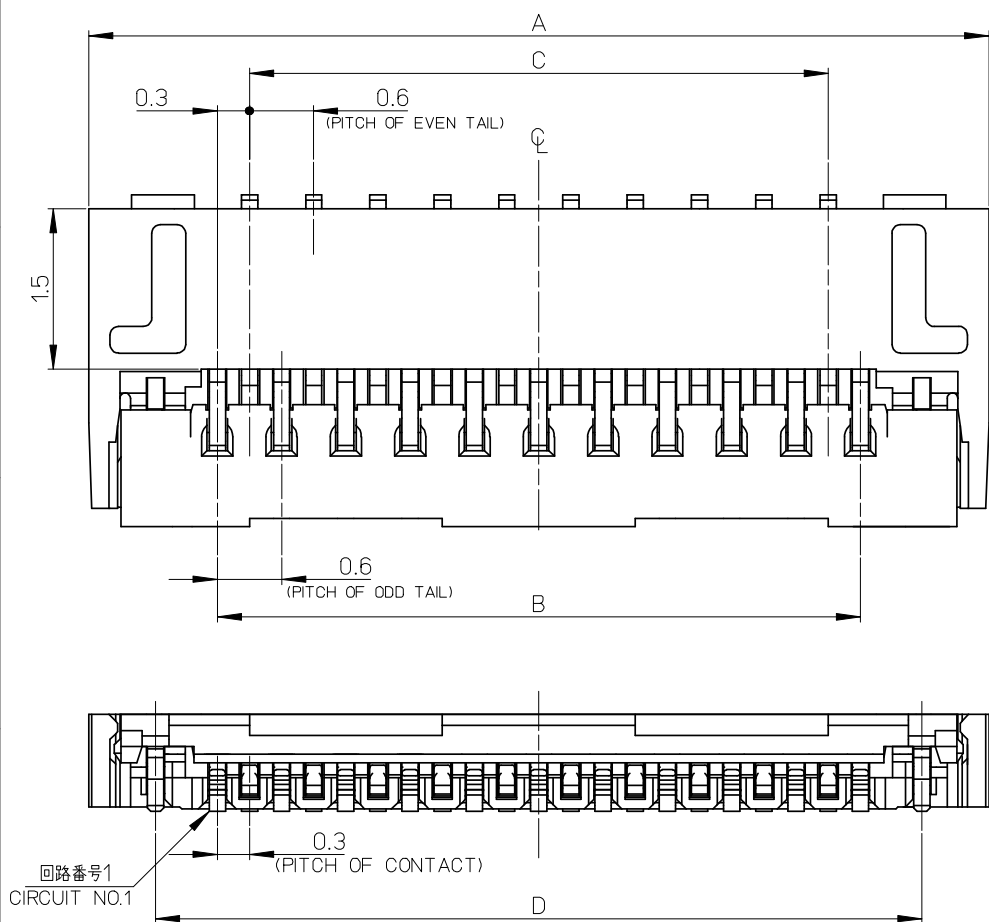
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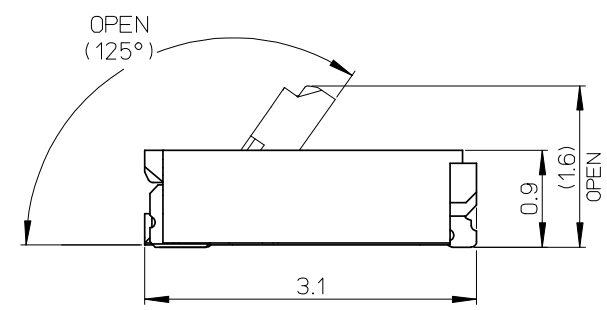
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注記
NOTES:
1.材質
MATERIAL
ハウジング: LCP (液晶ポリマー)、ガラス充填、UL94V-0
HOUSING: LCP (LIQUID CRYSTAL POLYMER),
GLASS FILLED, UL94V-0
アクチュエータ: ナイロン、ガラス充填、UL94V-0
ACTUATOR: NYLON (POLYAMIDE),
GLASS FILLED, UL94V-0
ターミナル: 銅合金 (t=0.15)
TERMINAL: COPPER ALLOY (t=0.15)
金具: 銅合金 (t=0.15)
NAIL: COPPER ALLOY (t=0.15)

2.めっき仕様
PLATING
ターミナル
TERMINAL
部分金めっき
SEPARATED GOLD PLATING
下地ニッケルめっき
UNDER PLATING: NICKEL PLATING
金具
NAIL
鍍めっき
TIN PLATING
下地ニッケルめっき
UNDER PLATING: NICKEL PLATING
3.平坦度は、0.1ミリ以下とする。
TAILS COPLANARITY TO BE 0.1 MAXIMUM.
4.ELV及びRoHS適合品
ELV AND RoHS COMPLIANT



0.10	16.15	14.4	15	17.4	501628-5191	501628-5111	51
0.089	14.35	12.6	13.2	15.6	501628-4591	501628-4511	45
0.078	12.55	10.8	11.4	13.8	501628-3991	501628-3911	39
0.071	11.35	9.6	10.2	12.6	501628-3591	501628-3511	35
0.067	10.75	9.0	9.6	12.0	501628-3391	501628-3311	33
0.064	10.15	8.4	9	11.4	501628-3191	501628-3111	31
0.056	8.95	7.2	7.8	10.2	501628-2791	501628-2711	27
0.046	7.15	5.4	6	8.4	501628-2191	501628-2111	21
重さ (g) WEIGHT (g)	D	C	B	A	オーダー番号 ORDER No.	製品番号 MATERIAL NO.	極数 CIRCUITS

REVISED
EC NO: J2009-0330
DRW: KUSATO
CHK: HSHIMOYAMA
APPR: HHIRATA

2008/08/04
2008/08/04
2008/08/05

DESCRIPTION
J

GENERAL TOLERANCES
(UNLESS SPECIFIED)
10 UNDER ±0.2
10 OVER 30 UNDER ±0.25
30 OVER ±0.3
ANGULAR ±1 °
DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY
DRAWN BY DATE
HSHIMOYAMA 2005/03/25
CHECKED BY DATE
HHIRATA 2005/03/25
APPROVED BY DATE
MSASAO 2005/03/25
MATERIAL NO.
SEE TABLE
SIZE
A3

SCALE
40:1
DESIGN UNITS
METRIC
THIRD ANGLE
PROJECTION
0.3 FPC CONN. (H=0.9)
HS'G ASSY BOTTOM CONTACT
NICKEL BARRIER
MOLEX INCORPORATED
DOCUMENT NO.
SD-501628-001
SHEET NO.
1 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX
INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

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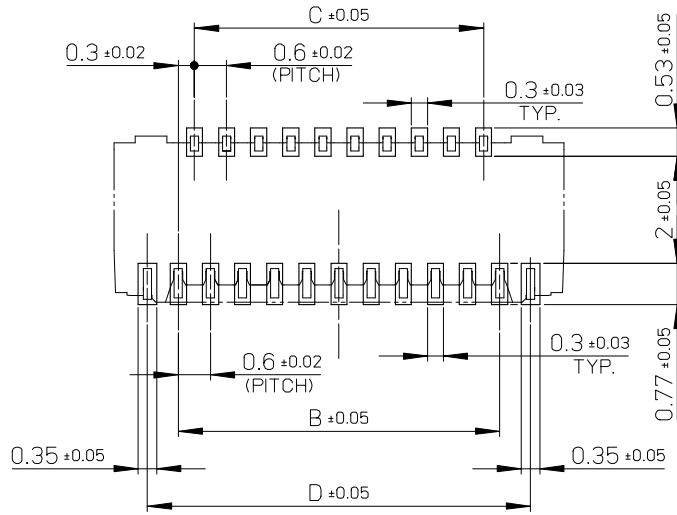
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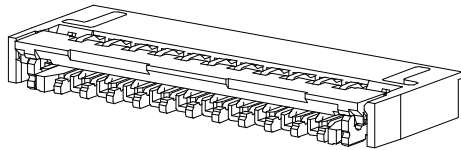
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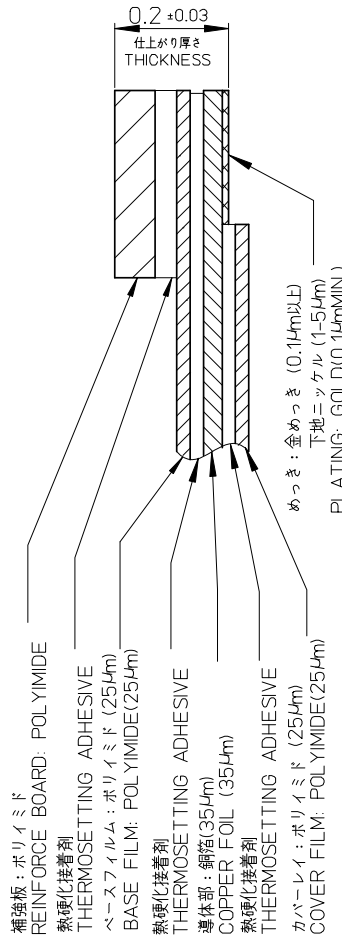
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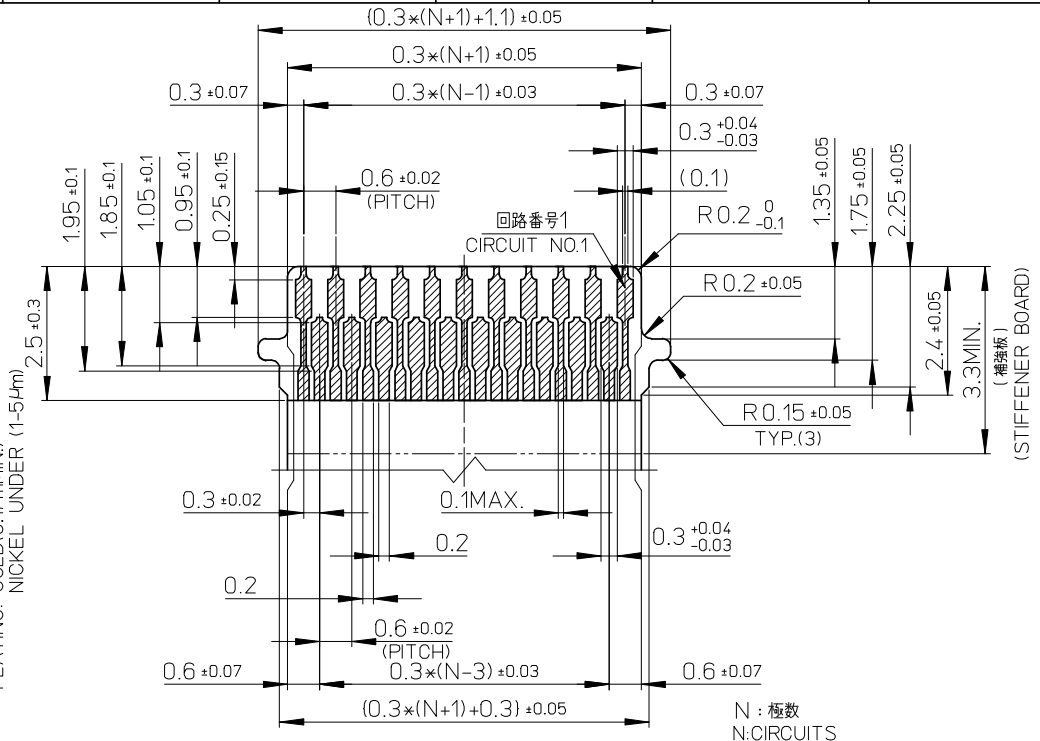
推奨基板寸法
RECOMMENDED P.C.B. PATTERN LAYOUT
(SCALE 5:1)



ISO VIEW (参考)



FPC構成推奨仕様
STRUCTURE OF FPC



適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PATING
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.2 ± 0.03)
(THICKNESS: 0.2 ± 0.03)

FPCについて:

抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、
染み出しが無い様、お願い致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.

RECOMMENDED MATERIAL:

STIFFENER FILM: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT

PLEASE PUT APPROPRIATE AMOUNT OF ASHESIVE ON THE
CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE
THE DEFECT IN ELECTRICAL CONTINUITY.

REVISED
EC NO: J2009-0330
DRW: KUSATO
CHK: HSHIMOTOYAMA
APPR: HIRATA
2008/08/04
2008/08/04
2008/08/05

DESCRIPTION
REV

GENERAL TOLERANCES
(UNLESS SPECIFIED)

10 UNDER	± 0.2
10 OVER 30 UNDER	± 0.25
30 OVER	± 0.3
ANGULAR	$\pm 1^\circ$
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE
MM ONLY

DRAWN BY	DATE
HSHIMOTOYAMA	2005/03/25
CHECKED BY	DATE
HIRATA	2005/03/25
APPROVED BY	DATE
MSASAO	2005/03/25

MATERIAL NO.
SEE TABLE

SIZE
A3

SCALE
40:1

TITLE

DESIGN UNITS
METRIC

THIRD ANGLE
PROJECTION

0.3 FPC CONN. (H=0.9)
HS'G ASSY BOTTOM CONTACT
NICKEL BARRIER

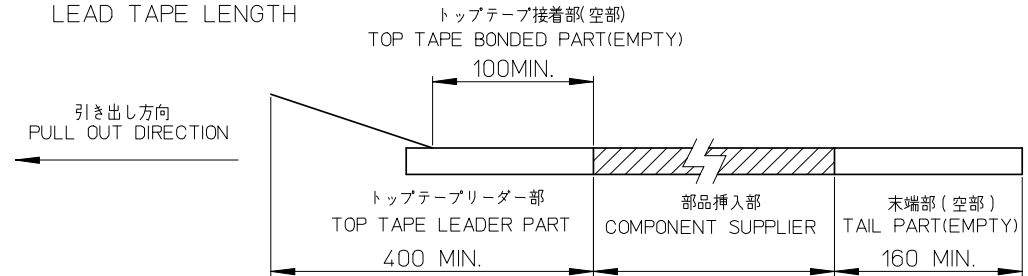
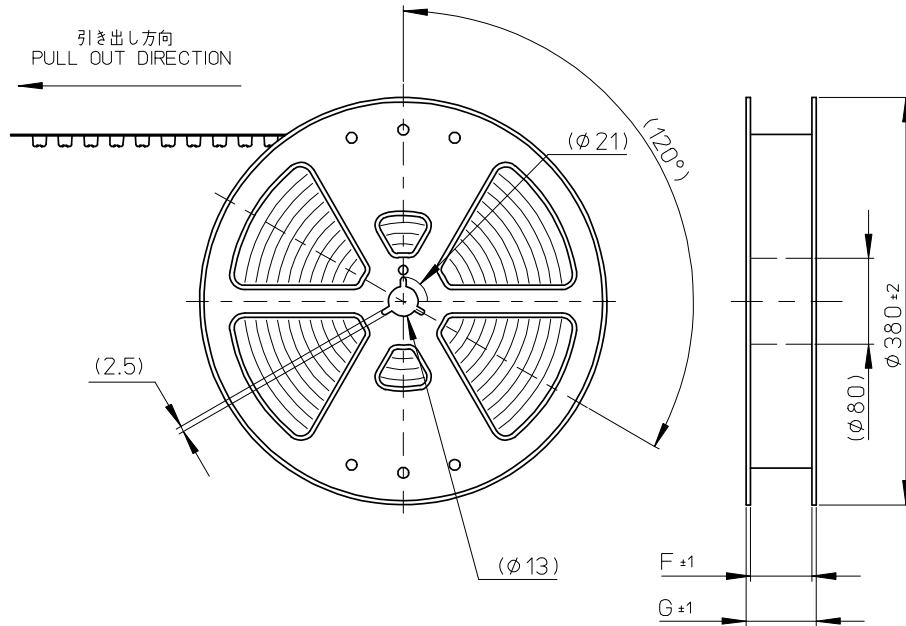
MOLEX INCORPORATED

DOCUMENT NO.
SD-501628-001

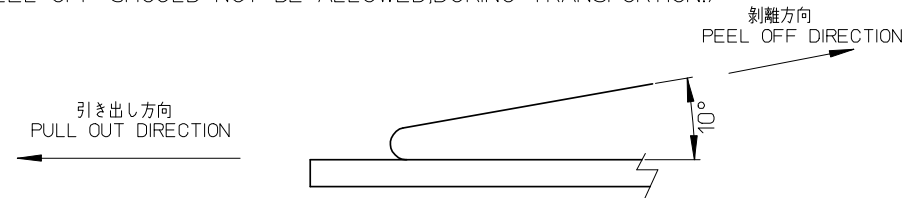
SHEET NO.
2 OF 2

注記)
NOTES

- 製品番号501628-**11の詳細寸法は、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 501628-**11 DETAIL DIMENSIONS,
SEE SALES DRAWING FOR CONNECTOR.
- 梱包数量:3000個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- トップテープの剥離強度 (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE (PEELING DIRECTION AS SHOWN IN FOLLOWING FIGURE)
0.1-1.3N (10-130gf)
尚、本規格値は出荷時に適用。
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
(但し、輸送時に剥離が発生しないこと)
(PEEL OFF SHOULD NOT BE ALLOWED,DURING TRANSPORTION.)



- 材料
MATERIAL
キャリアテープ:ポリスチレン (PS)
CARRIER TAPE:POLYSTYRENE(PS)
トップテープ:PET、PE、PEF
TOP TAPE :PET,PE,PEF
リール:ポリスチレン
REEL:POLYSTYLENE

- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

REVISED EC NO: J2009-0330 DRAWN:KUSATO CHKD:HSIMOYAMA APPR:HHIRATA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY HSHIMOYAMA	DATE 2005/08/22	TITLE 0.3 FPC CONN.(FOR 501628 -**11) TAPING PACKAGE NICKEL BARRIER				
		10 OVER 30 UNDER	± ---	CHECKED BY HHIRATA	DATE 2005/08/22					
		30 OVER	± ---	APPROVED BY MSASAO	DATE 2005/08/22	MOLEX INCORPORATED				
		ANGULAR	± --- °	MATERIAL NO.						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-501628-003			1 OF 2	
	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

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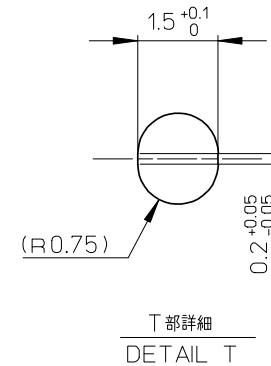
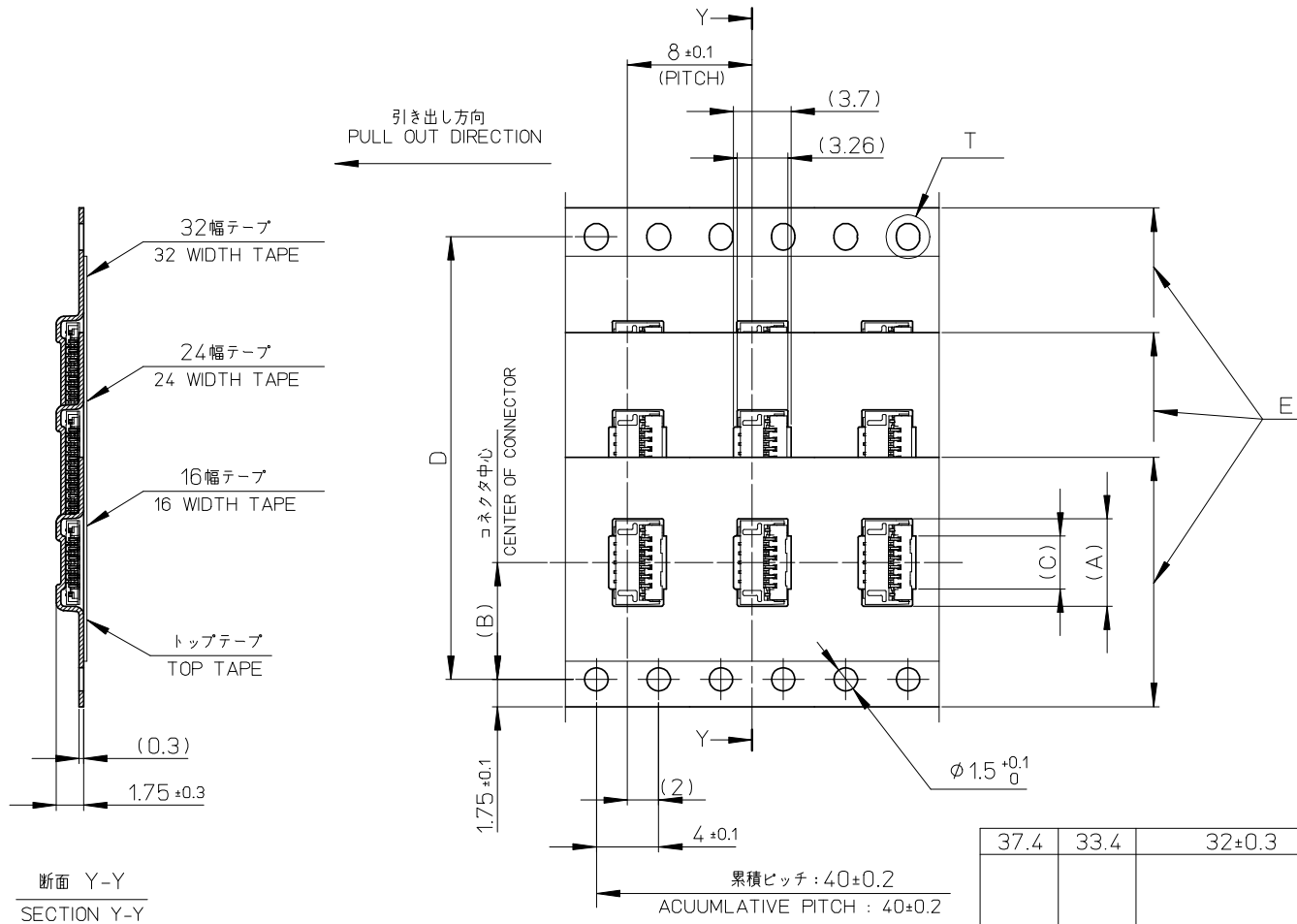
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37.4	33.4	32±0.3	28.4	15.4	14.2	17.6	501628-5191	51
29.4	25.4	24±0.3	++	13.6	11.5	15.8	501628-4591	45
				11.8		14	501628-3991	39
				10.6		12.8	501628-3591	35
				10.0		12.2	501628-3391	33
				9.4		11.6	501628-3191	31
				8.2		10.4	501628-2791	27
21.4	17.4	16±0.3		6.4	7.5	8.6	501628-2191	21
G	F	E キャリアテープ幅 EMBOSSED TAPE WIDTH	D	C	B	A	製 品 番 号 MATERIAL NO.	極 数 CIRCUITS

REVISED EC NO: J2009-0330 DRWN:KUSATO CHKD:HSHIMOYAMA APPR:HHIRATA REV	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS		THIRD ANGLE PROJECTION
				MM ONLY		---	METRIC		
		10 UNDER	± ---	DRAWN BY	DATE	TITLE 0.3 FPC CONN.(FOR 501628 -**11) TAPING PACKAGE NICKEL BARRIER			
		10 OVER 30 UNDER	± ---	CHECKED BY	DATE				
		30 OVER	± ---	APPROVED BY	DATE	 MOLEX INCORPORATED			
		ANGULAR ±--- °		MATERIAL NO.					
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-501628-003		2 OF 2		
		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						